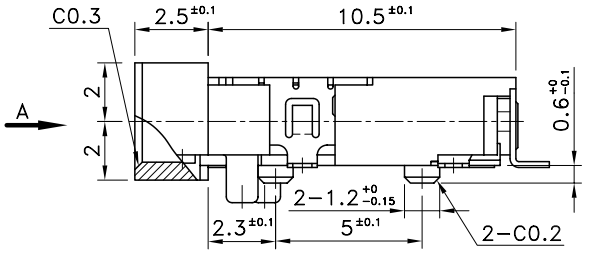
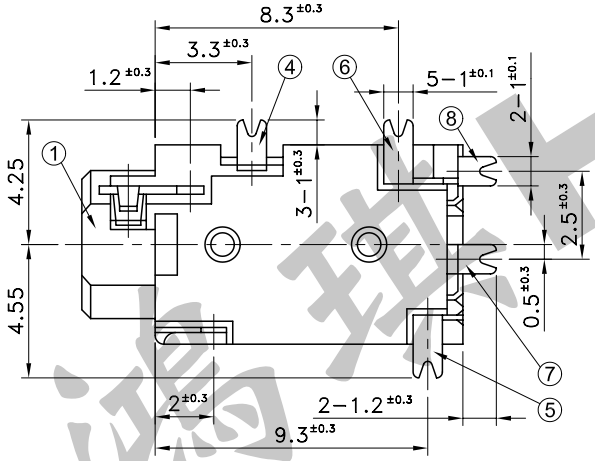
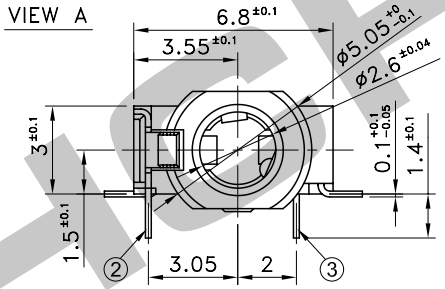
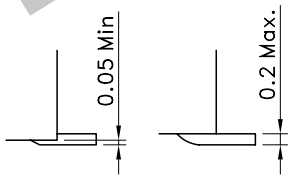
No.	Parts	Material	Q'ty	Finish	Remarks
8	Break Terminal No,1	t:0.2 Cu Alloy	1	Gold Plating Ep-Cu/Ni 1,Au 0.1/	
7	Break Terminal No,2	t:0.2 Cu Alloy	1	Gold Plating Ep-Cu/Ni 1,Au 0.1/	
6	Chip Terminal	t:0.2 Cu Alloy	1	Gold Plating Ep-Cu/Ni 1,Au 0.1/	
5	Ring Terminal	t:0.2 Cu Alloy	1	Gold Plating Ep-Cu/Ni 1,Au 0.1/	
4	Sleeve Terminal No,2	t:0.2 Cu Alloy	1	Gold Plating Ep-Cu/Ni 1,Au 0.1/	
3	Sleeve Terminal No,1	t:0.2 Cu Alloy	1	Gold Plating Ep-Cu/Ni 1,Au 0.1/	
2	Earth Terminal No,1	t:0.2 Cu Alloy	1	Gold Plating Ep-Cu/Ni 1,Au 0.1/	
1	Body	(PA)Polyamide	1		Black



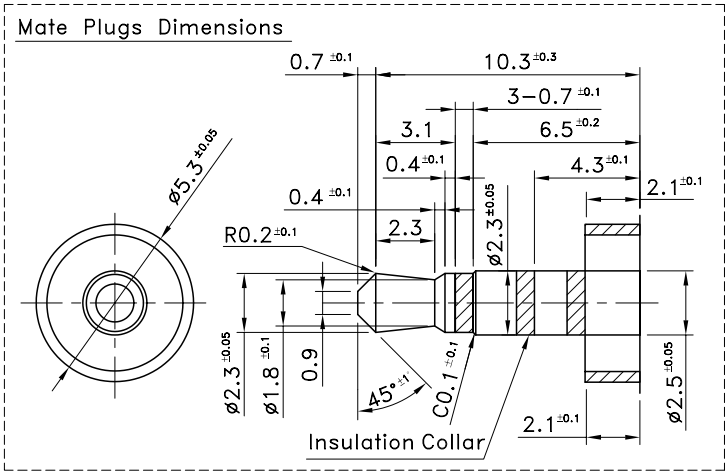


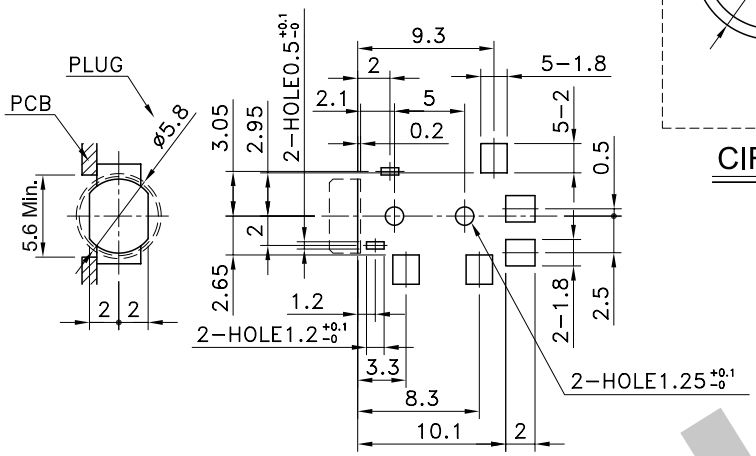
P.C.B TERMINAL POSITION



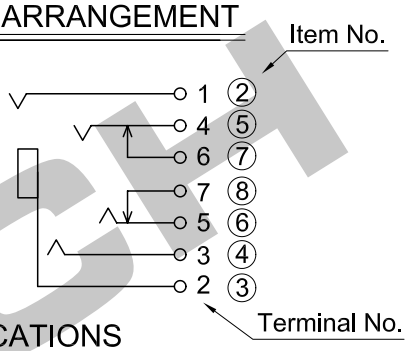


Coplanarity For All Terminal

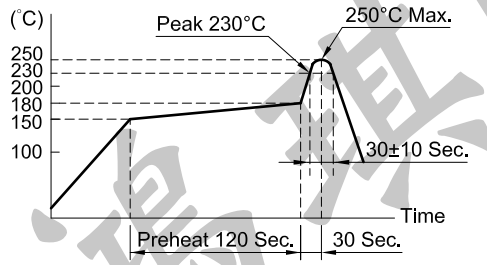




CIRCUIT ARRANGEMENT



REFLOW SOLDERING CONDITIONS



SPECIFICATIONS

1. Rating : DC 12V 1A
2. Contact Resistance : 30mΩ Max.
3. Insulation Resistance : 100MΩ Min. at DC 500V
4. Dielectric Strength : AC 500V for 1 Minute
5. Insertion & Extraction Force : 0.3~2.5kgf
6. Life : 10,000 Cycles
7. Taping : 700 Pcs/Reel
8. Operating Temperature Range :-30~+80°C
9. Reflow Soldering Profile : According Reflow Profile Max. 2 Times
   Metal Mask : t 0.12~0.18mm

REVISION:	DATE:	REVISION:	DATE:
UNIT:mm	THIRD ANGLE PROJECTION METHOD	TOL. UNLESS OTHERWISE STATED:±0.3	CODE NO.:HCH-908

ISSUED	CONFIRMED		PART NO.
John	Joey	HORNG CHIH	PJK-531
2005.03.24	2005.03.24	HCH® ISO9001 Certified ISO14001 Certified 鴻琪股份有限公司	

鴻琪 HCH